L Number	Hits	Search Text	DB	Time stamp
23	248	(((electrode near4 (embed\$6 protrud\$6 penetrat\$6	USPAT;	2004/08/04 08:19
		throughhole "through-hole" (through adj hole)))) same	US-PGPUB	
		(plat\$6 electroplat\$6 electroless)) and (((wafer substrate)		
		with (thin\$6 grind\$6 polish\$6 cmp)) same (organic adhe\$8		
		peel\$6 resist photoresist paste))		
24	81	(((electrode near4 (embed\$6 protrud\$6 penetrat\$6	USPAT;	2004/08/04 09:55
		throughhole "through-hole" (through adj hole)))) same	US-PGPUB	
		((wafer substrate) with (thin\$6 grind\$6 polish\$6 cmp)))		
		same (plat\$6 electroplat\$6 electroless)		
25	43	(438/667.ccls 257/621.ccls.) and (438/458.ccls.	USPAT;	2004/08/04 10:34
		438/459.ccls. 438/672.ccls. 438/675.ccls. 438/928.ccls.	US-PGPUB	
		438/977.ccls. 257/774.ccls.)		
27	4	ep-926723-\$.did. ep-1151962-\$.did.	USPAT;	2004/08/04 10:35
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
26	190	438/667.ccls 257/621.ccls.	USPAT;	2004/08/04 10:37
			US-PGPUB	
35	4	("5424245" "5946600" "6331208" "6605551"	USPAT	2004/08/04 12:13
	•	"2003/0082851" "2003/0203623").PN.		, ,
38	8	("3969745" "3986196" "4403241" "4445978"	USPAT	2004/08/04 12:17
	_	"4752555" "4842699" "4978639" "5053318").PN.		, ,
39	4	5260169.URPN.	USPAT	2004/08/04 12:20
44	15	("2770761" "3895967" "3897361" "3904442"	USPAT	2004/08/04 12:21
		"3979820" "4074342" "4239312" "4275410"		, ,
		"4370179" "4535424" "4660066" "4720308"		
		"4761681" "4773972" "4860084").PN.		
45	30	5528080.URPN.	USPAT	2004/08/04 12:27
49	4	("5243498" "5434094" "5488253" "5646067").PN.	USPAT	2004/08/04 12:33
50	i	6365513.URPN.	USPAT	2004/08/04 12:38
53	11	("3323198" "3484341" "3562009" "4089992"	USPAT	2004/08/04 12:45
		"4153988" "4211603" "4348253" "4403241"		, , ,
		"4426767" "4467521" "4512829").PN.		
54	38	4978639.URPN.	USPAT	2004/08/04 12:46
57	46	("3171762" "3256465" "3343256" "3372070"	USPAT	2004/08/04 12:52
·	,	"3418545" "3445686" "3454835" "3456335"		, ,
		"3462650" "3648131" "3761782" "3796927"		
		"3798513" "3885196" "3959579" "3962052"		
		"3969745" "3982268" "4074342" "4097890"		
		"4104674" "4188709" "4263341" "4275410"		
		"4368503" "4379307" "4467343" "4528072"		
		"4613891" "4670764" "4720738" "4761681"		
		"4765864" "4839309" "4839510" "4862322"		
		"4897708" "4954875" "4978639" "5024966"		
		"5166097" "5198698" "5268326" "5322816"		
		"5420064" "5443661").PN.		
58	84	5646067.URPN.	USPAT	2004/08/04 12:57
67	27	5618752.URPN.	USPAT	2004/08/04 12:59
68	45	("3171762" "3256465" "3343256" "3372070"	USPAT	2004/08/04 13:01
00	73	"3418545" "3445686" "3454835" "3456335"	OSIAI	2001/00/01 15:01
		"3462650" "3648131" "3761782" "3796927"		
		3462650 3646131 3761762 3750527 "3798513" "3885196" "3959579" "3962052"		
		3798513" 3885196 3959579 3962032 "3969745" "3982268" "4074342" "4097890"		
		"4104674" "4188709" "4263341" "4275410" "4369503" "4270307" "4467343" "4538073"	1	
		"4368503" "4379307" "4467343" "4528072"	1	
		"4613891" "4670764" "4720738" "4761681"		
		"4765864" "4839309" "4839510" "4862322"		
		"4897708" "4954875" "4978639" "5024966"		
		"5166097" "5198695" "5268326" "5322816"		
		"5420064").PN.		

				0004/00/04/0
73	10	("3648131" "4754316" "4761681" "4807021"	USPAT	2004/08/04 13:02
		"4954875" "5037782" "5059553" "5139969"		
		"5229647" "5366589").PN.		
74	63	5424245.URPN.	USPAT	2004/08/04 13:03
-	4	jp-2001326326-\$.did. jp-10074891-\$.did.	USPAT;	2004/08/03 15:33
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
_	4848	438/458.ccls. 438/459.ccls. 438/667.ccls. 438/672.ccls.	USPAT;	2004/08/04 10:11
	""	438/675.ccls. 438/928.ccls. 438/977.ccls. 257/621.ccls.	US-PGPUB	
		257/774.ccls.		
_	22013	(electrode near4 (embed\$6 protrud\$6 penetrat\$6	USPAT;	2004/08/03 15:40
	22013	throughhole "through-hole" (through adj hole)))	US-PGPUB	220 ,, 20, 20 22
	32009	(electrode with (embed\$6 protrud\$6 penetrat\$6 throughhole	EPO; JPO;	2004/08/03 15:41
-	32009		DERWENT;	200 1/00/03 13.11
		"through-hole" (through adj hole)))		
	1010	(1) I I I I I I I I I I I I I I I I I I I	IBM_TDB	2004/08/03 17:18
-	1818	((electrode with (embed\$6 protrud\$6 penetrat\$6	EPO; JPO;	2004/06/03 17:16
		throughhole "through-hole" (through adj hole)))) and	DERWENT;	
		((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6	IBM_TDB	
		etch\$6 cmp))		0004/00/00 47 40
-	360	(((electrode with (embed\$6 protrud\$6 penetrat\$6	EPO; JPO;	2004/08/03 17:19
		throughhole "through-hole" (through adj hole)))) and	DERWENT;	
1		((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6	IBM_TDB	
		etch\$6 cmp))) and (plat\$6 electroplat\$6 electroless)		
-	1004	((electrode near4 (embed\$6 protrud\$6 penetrat\$6	USPAT;	2004/08/03 17:21
		throughhole "through-hole" (through adj hole)))) same	US-PGPUB	
		((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6		
1		etch\$6 cmp))		
-	169	(((electrode near4 (embed\$6 protrud\$6 penetrat\$6	USPAT;	2004/08/03 15:51
		throughhole "through-hole" (through adj hole)))) same	US-PGPUB	
		((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6		
		etch\$6 cmp))) same (plat\$6 electroplat\$6 electroless)		
i _	4338	((electrode near4 (embed\$6 protrud\$6 penetrat\$6	USPAT;	2004/08/03 17:22
	1555	throughhole "through-hole" (through adj hole)))) same	US-PGPUB	
		(plat\$6 electroplat\$6 electroless)		
	1082	(((electrode near4 (embed\$6 protrud\$6 penetrat\$6	USPAT;	2004/08/03 15:52
	1002	throughhole "through-hole" (through adj hole)))) same	US-PGPUB	' '
		(plat\$6 electroplat\$6 electroless)) and ((wafer substrate)		
		with (thin\$6 remov\$6 grind\$6 polish\$6 etch\$6 cmp)) and		
		(organic adhe\$8 peel\$6 resist photoresist paste)		
	F24	(((electrode near4 (embed\$6 protrud\$6 penetrat\$6	USPAT;	2004/08/03 17:20
-	531	throughhole "through-hole" (through adj hole)))) same	US-PGPUB	200 1/00/00 17:20
		(plat\$6 electroplat\$6 electroless)) and (((wafer substrate)	0510100	
		(plats b electropiats b electroless)) and (((water substrate)		
		with (thin\$6 remov\$6 grind\$6 polish\$6 etch\$6 cmp)) same		
	356	(organic adhe\$8 peel\$6 resist photoresist paste))	USPAT;	2004/08/03 15:55
-	356	(((electrode near4 (embed\$6 protrud\$6 penetrat\$6		2004/06/03 13.33
		throughhole "through-hole" (through adj hole)))) same	US-PGPUB	
		(plat\$6 electroplat\$6 electroless)) and (((wafer substrate)		
		with (thin\$6 remov\$6 grind\$6 polish\$6 etch\$6 cmp)) with		
		(organic adhe\$8 peel\$6 resist photoresist paste))	LICDAT	2004/00/02 45:57
-	39	((((electrode near4 (embed\$6 protrud\$6 penetrat\$6	USPAT;	2004/08/03 15:57
		throughhole "through-hole" (through adj hole)))) same	US-PGPUB	
		((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6		
		etch\$6 cmp))) same (plat\$6 electroplat\$6 electroless))		
		same (organic adhe\$8 peel\$6 resist photoresist paste)	1	
-	100	(438/458.ccls. 438/459.ccls. 438/667.ccls. 438/672.ccls.	USPAT;	2004/08/03 16:26
		438/675.ccls. 438/928.ccls. 438/977.ccls. 257/621.ccls.	US-PGPUB	
		257/774.ccls.) and (electrode near2 (embed\$6 protrud\$6		
	<u> </u>	penetrat\$6 throughhole "through-hole" (through adj hole)))		

	110	((((electrode with (embed\$6 protrud\$6 penetrat\$6	EPO; JPO;	2004/08/03 17:04
-	110			2004/06/03 17.04
		throughhole "through-hole" (through adj hole)))) and	DERWENT;	
		((wafer substrate) with (thin\$6 remov\$6 grind\$6 polish\$6	IBM_TDB	
		etch\$6 cmp))) and (plat\$6 electroplat\$6 electroless)) and		
		(organic adhe\$8 peel\$6 resist photoresist paste)		
-	1532	((electrode with (embed\$6 protrud\$6 penetrat\$6	EPO; JPO;	2004/08/03 17:19
		throughhole "through-hole" (through adj hole)))) and	DERWENT;	
		((wafer substrate) with (thin\$6 grind\$6 polish\$6 etch\$6	IBM_TDB	
		cmp))		
-	903	((electrode with (embed\$6 protrud\$6 penetrat\$6	EPO; JPO;	2004/08/03 17:19
		throughhole "through-hole" (through adj hole)))) and	DERWENT;	
		((wafer substrate) with (thin\$6 grind\$6 polish\$6 cmp))	IBM_TDB	
-	521	((electrode near4 (embed\$6 protrud\$6 penetrat\$6	USPAT;	2004/08/03 17:22
		throughhole "through-hole" (through adj hole)))) same	US-PGPUB	
		((wafer substrate) with (thin\$6 grind\$6 polish\$6 cmp))		
-	163		EPO; JPO;	2004/08/03 18:01
		throughhole "through-hole" (through adj hole)))) and	DERWENT;	
		((wafer substrate) with (thin\$6 grind\$6 polish\$6 cmp))) and	IBM_TDB	
		(plat\$6 electroplat\$6 electroless)	_	